

IN THE CLAIMS:

Please amend the claims as follows:

Claims 1-26 are canceled.

Claim 27: (Original) A method for manufacturing a semiconductor die package, comprising:

molding a package base including a plurality of side walls and a floor having a plurality of holes formed therethrough, wherein interior surfaces of the side walls and floor form a cavity sized to hold a semiconductor die and wherein said molding includes molding an electrically conductive frame into the floor, said frame having a plurality of holes formed therein and the holes through the floor register with the holes of said frame; and

inserting electrically-conductive pins into the holes in the floor such that the pins pass into the holes of the frame and extend from an exterior surface of the floor.

Claim 28: (Original) The method of claim 27, further comprising:

electrically connecting a semiconductor die to the pins and to the frame; and
attaching a lid to the side walls of the base, the lid and the base sealing the semiconductor die therein.

Claim 29: (Original) The method of claim 28, wherein said step of electrically connecting comprises:

coupling solder balls to the pins and to the frame and coupling the semiconductor die to the solder balls.

Claim 30: (Original) The method of claim 28, wherein the step of electrically connecting comprises:

coupling solder balls to the pins and to the frame;
placing a substrate over the solder balls;
placing the semiconductor die on the substrate; and
electrically connecting the semiconductor die to the substrate.

Claim 31: (New) The method of claim 27, wherein the floor of the package base comprises an electrically insulative material and the frame is electrically insulated from at least some of the pins.

Claim 32: (New) A method for manufacturing a semiconductor die package, comprising:

forming a package base having a plurality of side walls, a floor, and an electrically-conductive grid having interconnecting rows and columns that define openings therebetween, wherein interior surfaces of the side walls and floor form a cavity sized to hold a semiconductor die, and wherein the forming comprises molding an insulative material to form at least a portion of the floor and attaching the electrically-conductive grid to the portion of the floor; and

providing electrically-conductive paths extending from an exterior surface of the floor, wherein at least some of the paths are provided through the openings of the electrically-conductive grid.

Claim 33: (New) The method of claim 32, further comprising:

inserting a semiconductor die into the cavity; and
sealing the semiconductor die within the cavity.

Claim 34: (New) The method of claim 33, wherein the step of sealing comprises:

encapsulating the semiconductor die within the cavity.

Claim 35: (New) The method of claim 33, wherein the step of sealing comprises:

attaching a lid to the base so as to cover the cavity.

Claim 36: (New) The method of claim 32, wherein at least some of the electrically-conductive paths extending from an exterior surface of the floor electrically connect to the electrically-conductive grid.

Claim 37: (New) A method for manufacturing a semiconductor die package, comprising:

forming a package base having a plurality of side walls, a floor, and an electrically-conductive grid having interconnecting rows and columns that define openings therebetween, wherein interior surfaces of the side walls and floor form a cavity sized to hold a semiconductor die, and wherein the forming comprises molding the electrically-conductive grid into at least a portion of the floor; and

providing electrically-conductive paths extending from an exterior surface of the floor, wherein at least some of the paths are provided through the openings of the electrically-conductive grid.

Claim 38: (New) The method of claim 37, further comprising:

inserting a semiconductor die into the cavity; and
sealing the semiconductor die within the cavity.

Claim 39: (New) The method of claim 38, wherein the step of sealing comprises:

encapsulating the semiconductor die within the cavity.

Claim 40: (New) The method of claim 38, wherein the step of sealing comprises:

attaching a lid to the base so as to cover the cavity.

Claim 41: (New) The method of claim 37, wherein at least some of the electrically-conductive paths extending from an exterior surface of the floor electrically connect to the electrically-conductive grid.